

Series: Ceramic Chip Antenna

TECHNICAL DATA SHEET

Description: 1.575 GHz GNSS Ceramic

Chip Antenna

PART NUMBER: W3011A

Features:

- Frequency 1559-1606.6MHz
- Gain 1.3 / 2.0 / 2.2dBi
- Size 3.2 x 1.6 x 1.1 mm
- PCB Keep out 4 x 6.25 mm
- Polarization Linear
- · Radiation pattern Omni

Applications:

- L1 GNSS Receivers
- Beidou, GPS, Galileo Glonass
- IoT, M2M
- Asset tracking
- Portable satellite receivers

All dimensions are in mm / inches

Issue: 2019

In the effort to improve our products, we reserve the right to make changes judged to be necessary. CONFIDENTIAL AND PROPRIETARY INFORMATION

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ELECTRICAL SPECIFICATIONS

Antenna Type Chip antenna

Frequency 1559-1563MHz

1574.4-1576.4MHz 1598.6-1606.6MHz

Nominal Impedance 50Ω

Return Loss (Max) -7 / -10 / -10 dB

Radiation Pattern Omni

Gain(Min) 1.3 / 2.0 / 2.2dBi

Efficiency(Min) 65 / 75 / 78 %

Polarization Vertical

Power Withstanding 2W

MECHANICAL SPECIFICATIONS

Compact size 3.2 x 1.6 x 1.1mm

Weight 0.033g
Fixing system SMT

MSL(MOISTURE SENSITIVITY LEVEL) 1

ENVIRONMENTAL SPECIFICATIONS

Operating Temperature $-40 \sim +85^{\circ}$ C Storage Temperature $-40 \sim +85^{\circ}$ C

RoHS Compliant Yes



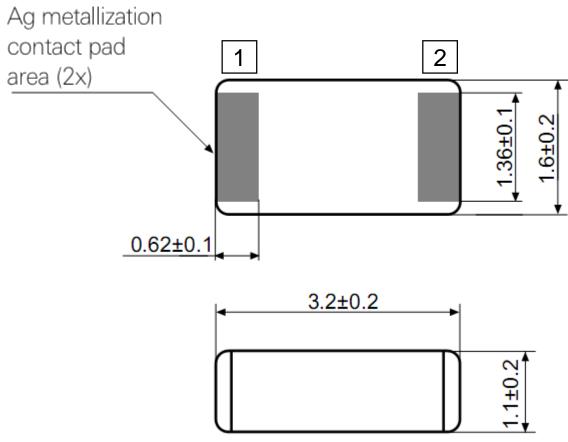
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MECHANICAL DRAWING



Antenna features

No.	Terminal name	Terminal Dimensions
1	Feed / GND	0.62 x 1.36 mm
2	Feed / GND	0.62 x 1.36 mm

Antenna is symmetrical.

Either of terminals 1 or 2 can be feed / GND





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W3011 GPS Antenna PWB Layout

Ground cleared under antenna, clearance area 4.00 x 6.25 mm Matching and tuning component value and placement depend on application and surrounding mechanics / materials.

Feed line should be designed to match 50 Ω characteristic impedance, depending on PWB material and thickness.

Recommended test board layout for electrical characteristic measurement, test board outline size 80 x 37 mm.





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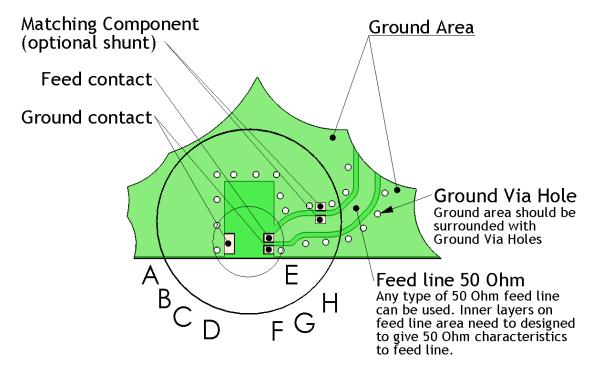
Chip Antenna

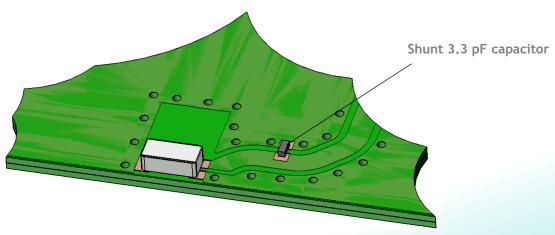
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PWB layout for W3011A GPS Antenna

Note: All dimensions are in metric system.









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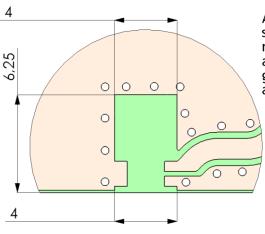
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Ground clearance area for W3011A GPS Antenna

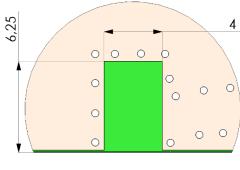
Ground clearance area (4,00 x 6,25 mm)



All metallization should be removed from all PWB layers on ground clearance area (4,00 x 6,25 mm).

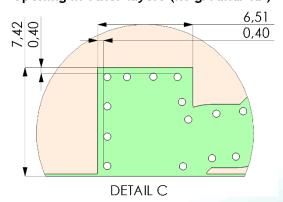
DETAIL A

Opening in bottom/inner ground layers



DETAIL B

Opening in other layers (no ground/RF)





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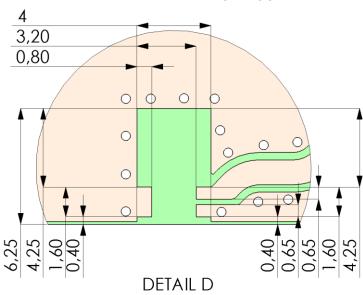
Chip Antenna

PART NUMBER: W3011A

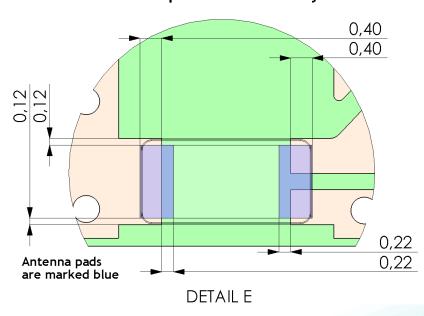
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PWB pad dimensions and antenna position for W3011A GPS Antenna

Pad dimensions in top copper



Antenna position on PWB layout





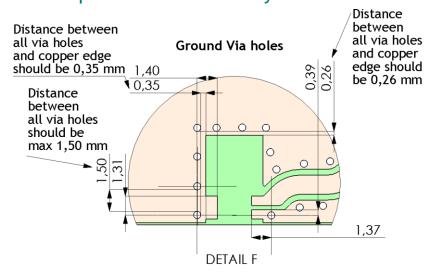
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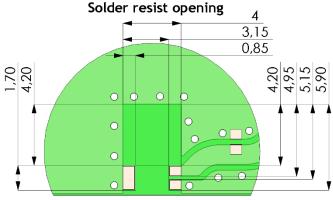
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Typical Ground via hole placement in PWB layout for W3011A GPS Antenna



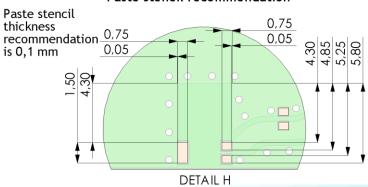
Solder resist opening and paste stencil recommendations for W3011A GPS





DETAIL G

Paste stencil recommendation



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ROHS



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TEST SETUP

All RF parameters tested on 80x37mm sized test board. Antenna position on side center of PCB long edge.



37mm

80mm





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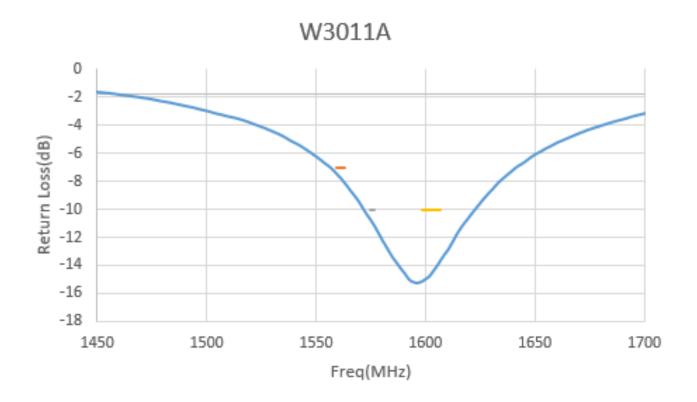
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CHARTS

Return Loss vs Frequency







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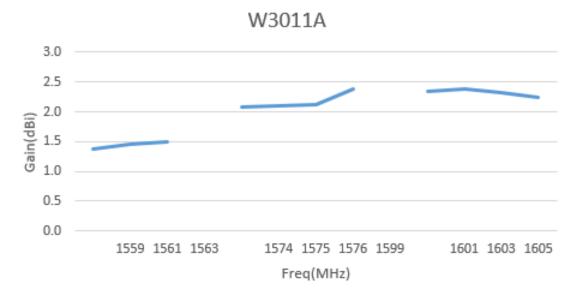
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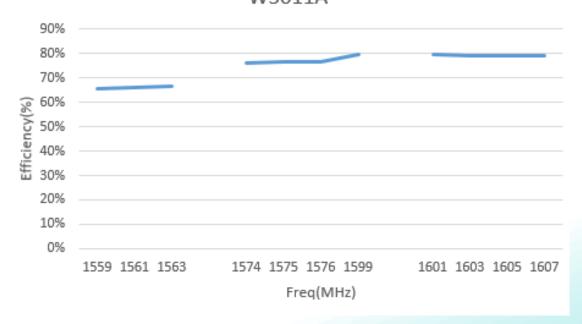
CHARTS

Gain vs Frequency



Radiation Efficiency vs Frequency

W3011A







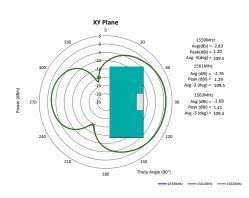
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Chip Antenna

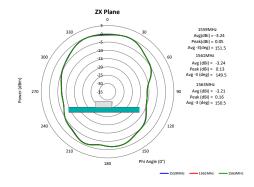
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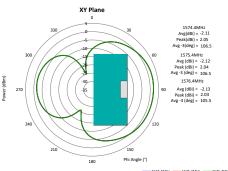
Series: Ceramic Chip Antenna

CHARTS

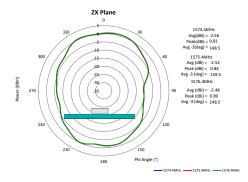


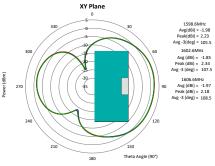
Beidou B1



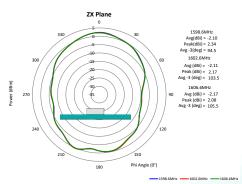


GPS L1





Glonass L1





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Recommendation for reflow soldering process

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures. located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection	
1	Average temperature gradient in preheating	2.5 °C/s	
2	Soak time	2-3 minutes	
3	Max temperature gradient in reflow	3 °C/s	
4	Time above 217 °C	Max 30 sec	
5	Peak temperature in reflow	230 °C for 10 seconds	
6	Temperature gradient in cooling	Max -5 °C/s	

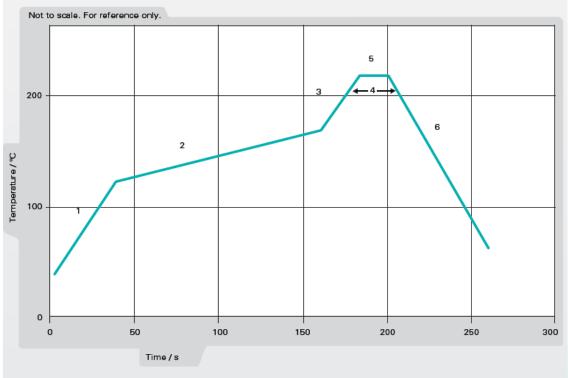


Figure 1. Minimum temperature profile recommendation for reflow soldering process

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Recommendation for reflow soldering process

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 60 sec
5	Time above 230 °C	Max 50 sec
6	Time above 250 °C	Max 10 sec
7	Peak temperature in reflow	260 °C for 5 seconds
8	Temperature gradient in cooling	Max -5 °C/s

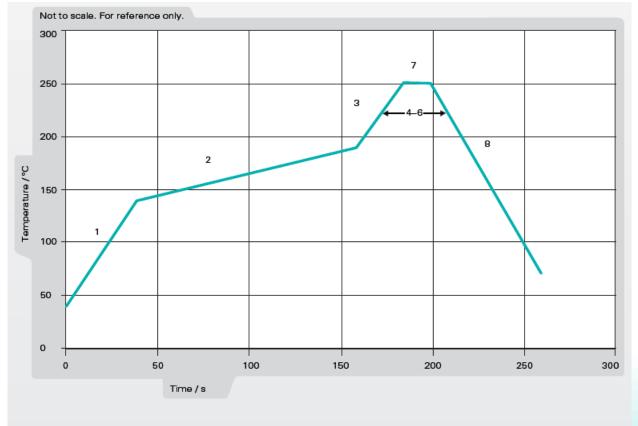


Figure 2. Maximum temperature profile recommendation for reflow soldering process



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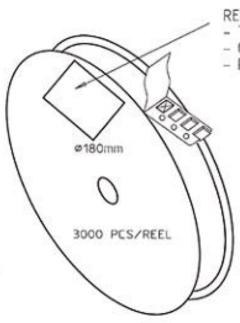
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PACKAGING

Taping package 3000PCS/Reel 30000PCS/Carton box



REEL LABEL INFORMATION:

- TRACEABILITY
- QUANTITY
- PRODUCT CODE

CARRIER TAPE H85-00125 width=8,00 depth=1,22 COVER TAPE H85-00126 width=5,60

LENGTH OF TAPE:

- Leader section: 50 empty cavities before component section
- Trailer section: 25 empty cavities after component section.

Empty part cavities at leader and trailer section of the tape must be sealed with top cover tape.

BOX H85-00128 (182x182x132) 1 pcs

- LABEL

1 pcs/BOX

REEL H85-00127

10 pcs

(D180, W12)

- REEL LABEL

1 pcs/REEL



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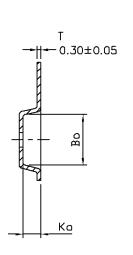
Chip Antenna

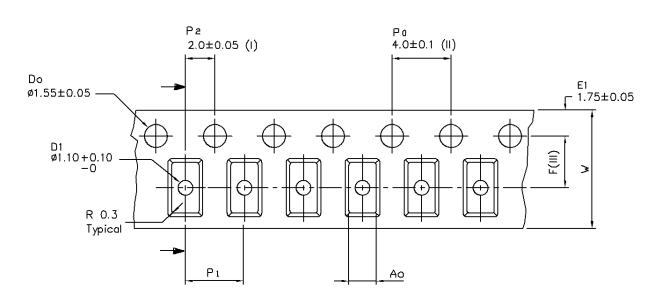
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PACKAGING

Tape size





Ao	1.85	+/- 0.1
Во	3.43	+/- 0.1
Ко	1.22	+/- 0.1
F	3.50	+/- 0.05
P ₁	4.00	+/- 0.1
W	8.00	+/- 0.1

